

7-CHANNEL INTEGRATED ESD SOLUTION FOR VGA PORT WITH INTEGRATED LEVEL SHIFTER AND MATCHING IMPEDANCE

Check for Samples: [TPD7S019](#)

FEATURES

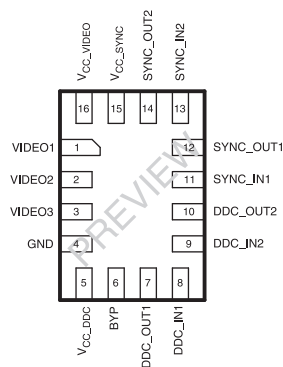
- 7-Channel ESD Protection Includes ESD Protection, Level-Shifting, Buffering and Sync Impedance Matching
- Exceeds IEC61000-4-2 (Level 4) ESD Protection to Requirements on the External Pins
 - ±15-kV Human-Body Model (HBM)
 - ±8-kV IEC 61000-4-2 Contact Discharge
- Very Low Loading Capacitance from ESD Protection Diodes on VIDEO Lines (2.5 pF)
- 5-V Drivers for HSYNC and VSYNC Lines
- Integrated Impedance Matching Resistors on Sync Lines:
 - TPD7S019-65: 65-Ω Termination
 - TPD7S019-15: 15-Ω Termination
 - TPD7S019-55: 55-Ω Termination

- Bi-Directional Level Shifting N-Channel FETs Provided for DDC_CLK and DDC_DATA Channels
- Flow-Through Single-In-Line Pin Mapping Ensures no Additional Board Layout Burden while Placing the ESD Protection Chip Near the Connector

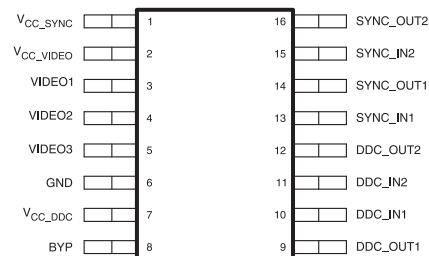
APPLICATIONS

- VGA and DVI-I Ports in:
 - Desktop and Notebook PCs
 - Graphics Cards
 - Set Top Boxes
 - TV

**RSV PACKAGE
(TOP VIEW)**



**DBQ PACKAGE
(TOP VIEW)**



ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾ ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	μQFN – RSV	Tape and reel	TPD7S019-15RSVR
	SSOP/QSOP – DBQ	Tape and reel	TPD7S019-15DBQR
			TPD7S019-55DBQR
			TPD7S019-65DBQR
			PREVIEW

- (1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
 (2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.



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TERMINATION AT SYNC	PITCH	LENGTH (TYP)	WIDTH (TYP)	HEIGHT (MAX)	ORDERABLE PART NO.
15-Ω	0.635 mm	4.9 mm	6.0 mm	1.75 mm	TPD7S019-15DBQR
55-Ω					TPD7S019-55DBQR
65-Ω					TPD7S019-65DBQR
15-Ω	0.4 mm	2.6 mm	1.8 mm	0.55 mm	TPD7S019-15RSVR

DESCRIPTION/ORDERING INFORMATION

The TPD7S019 is an integrated 7-channel ESD solution for the VGA or DVI-I port connector. This device integrates ESD protection for all signals, level shifting for the DDC signals and buffering for the SYNC signals.

Three individual supply lines control the power rails of the VIDEO, DDC and SYNC channels to facilitate interfacing with low voltage video controller ICs in mixed supply-voltage environments.

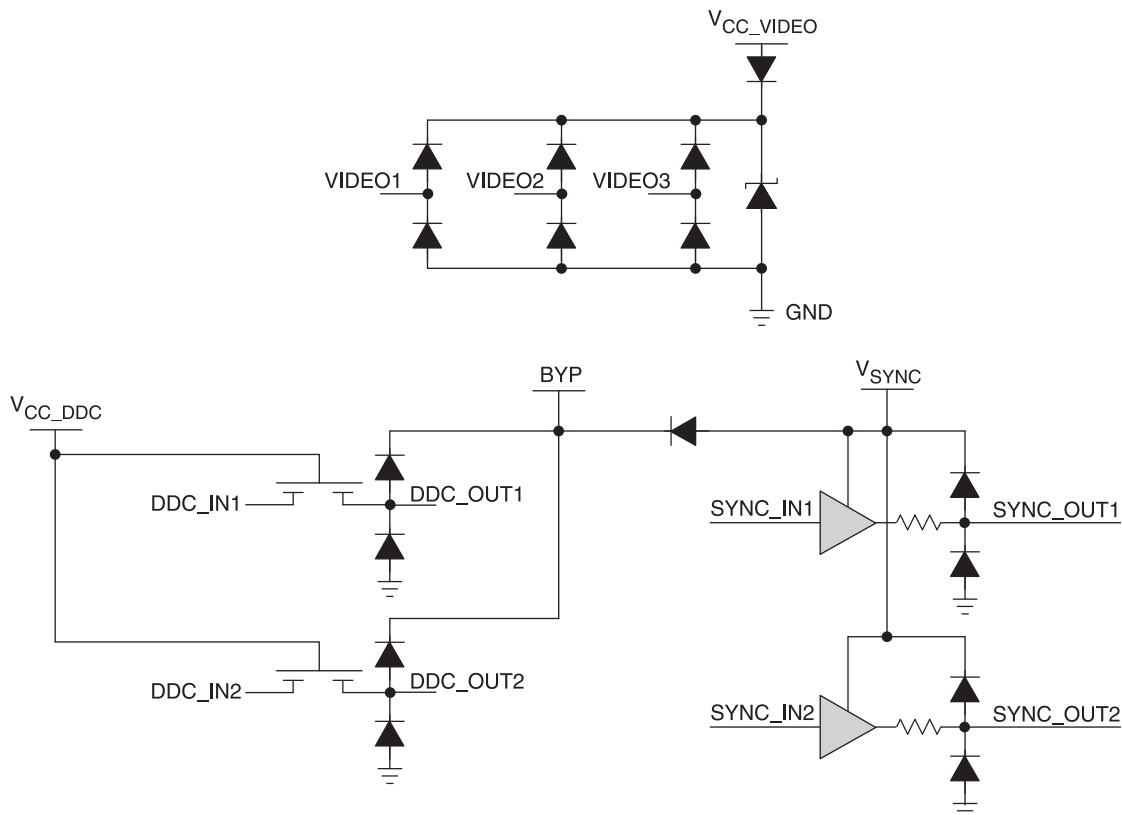
Two non-inverting drivers provide buffering for the HSYNC and VSYNC signals from the video controller IC (SYNC1, SYNC2). These buffers accept TTL input levels and convert them to CMOS output levels that swing between Ground and VCC_SYNC, which is typically 5 V. Additionally, each driver has a series termination resistor (RT) connected to the SYNC_OUT pin, eliminating the external termination resistors typically required for the HSYNC and VSYNC lines of the video cable. At the SYNC output the TPD7S019 offers 65-Ω, 55-Ω, or 15-Ω series termination resistor option to match different transmission line impedances.

Two N-channel MOSFETs provide the level shifting function required when the DDC controller is operated at a lower supply voltage than the monitor. The gate terminals for the MOSFETs (VCC_DDC) should be connected to the supply rail (typically 3.3 V) that supplies power to the transceivers of the DDC controller.

The TPD7S019 confirms the IEC61000-4-2 (Level 4) system level ESD protection and ±15KV HBM ESD protection. This device is offered in space-saving 16-pin DBQ and 16-pin RSV packages.

The TPD7S019 is characterized for operation over ambient air temperature of –40°C to 85°C.

CIRCUIT DIAGRAM



TERMINAL FUNCTIONS

TERMINAL			TYPE	DESCRIPTION
NAME	NO.			
	DBQ	RSV		
BYP	8	6	Power	Bypass pin. Using a 0.2 μ F bypass capacitor will increase the ESD robustness of the system.
DDC_IN1 DDC_IN2	10 11	8 9	I	DDC signal input. Connects to the VGA controller side of one of the sync lines.
DDC_OUT1 DDC_OUT2	9 12	7 10	O	DDC signal output. Connects to the video connector side of one of the sync lines.
GND	6	4	–	Ground
SYNC_IN1 SYNC_IN2	13 15	11 13	I	Sync signal buffer input. Connects to the VGA controller side of one of the sync lines.
SYNC_OUT1 SYNC_OUT2	14 16	12 14	O	Sync signal buffer output. Connects to the video connector side of one of the sync lines
VCC_DDC	7	5	Power	Isolated supply input for the DDC_1 and DDC_2 level-shifting N-FET gates
VCC_SYNC	1	15	Power	Isolated supply input for the SYNC_1 and SYNC_2 level shifters and their associated ESD protection circuits
VCC_VIDEO	2	16	Power	Supply pin specifically for the VIDEO_1, VIDEO_2 and VIDEO_3 ESD protection circuits
VIDEO1 VIDEO2 VIDEO3	3 4 5	1 2 3	ESD	High-speed ESD clamp input

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC_VIDEO} , V_{CC_DDC} , V_{CC_SYNC}	Supply voltage		–0.5	6.0	V
$V_{IO(VIDEO)}$	IO voltage	VIDEOx pins	–0.5	V_{CC_VIDEO}	V
$V_{I(SYNC)}$	Input voltage	SYNC pins	–0.5	V_{CC_SYNC}	V
$V_{I(DDC)}$	Input voltage	DDC_INx pins	–0.5	6.0	V
$V_{O(DDC)}$	Output voltage	DDC_INx pins	–0.5	6.0	V
T_{stg}	Storage temperature		–55	125	°C
	IEC 61000-4-2 Contact Discharge	VIDEO, DDC_OUT, SYNC_OUT pins		± 8	kV
	HBM ESD	VIDEO, DDC_OUT, SYNC_OUT pins		± 15	kV
		VCC, DDC_IN, SYNC_IN, BYP Pins		± 2	kV

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC_VIDEO} , V_{CC_DDC} , V_{CC_SYNC}	Supply voltage		0	5.5	V
$V_{IO(VIDEO)}$	IO voltage	VIDEOx pins	0	V_{CC_VIDEO}	V
$V_{I(SYNC)}$	Input voltage	SYNC pins	0	V_{CC_SYNC}	V
$V_{I(DDC)}$	Input voltage	DDC_INx pins	0	5.5	V
$V_{O(DDC)}$	Output voltage	DDC_INx Pins	0	5.5	V
T_A	Operating temperature		–40	85	°C

ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITION	MIN	TYP	MAX	UNIT	
I_{CC_VIDEO}	V_{CC_VIDEO} supply current	$V_{CC_VIDEO} = 5\text{ V}$, VIDEO inputs at V_{CC_VIDEO} or GND		1	10	μA	
I_{CC_DDC}	V_{CC_DDC} supply current	$V_{CC_DDC} = 5\text{ V}$		1	10	μA	
I_{CC_SYNC}	V_{CC_SYNC} supply current	$V_{CC_SYNC} = 5\text{ V}$, SYNC inputs at GND or V_{CC_SYNC} , SYNC outputs unloaded		1	50	μA	
			SYNC inputs at 3 V; SYNC outputs unloaded			2.0	mA
I_{IO_VIDEO}	VIDEO input/output pins	$V_{IO_VIDEO} = 3\text{ V}$		0.01	1.0	μA	
I_{OFF}	DDC pin powerdown leakage current	$V_{CC_DDC} \leq 0.4\text{ V}$, $V_{DDC_OUT} = 5\text{ V}$		0.01	1.0	μA	
V_D	Diode forward voltage for lower clamp of VIDEO, DDC, SYNC output pins	$I_D = 8\text{ mA}$, lower clamp diode	-0.6	-0.8	-0.95	V	
R_{DYN_VIDEO}	Dynamic resistance (VIDEO pins)	$I = 1\text{ A}$		1.0		Ω	
V_{IH}	High-level SYNC logic input voltage	$V_{CC_SYNC} = 5\text{ V}$	2.0			V	
V_{IL}	Low-level SYNC logic input voltage	$V_{CC_SYNC} = 5\text{ V}$			0.6	V	
V_{OH}	High-level SYNC logic output voltage	$I_{OH} = 0\text{ mA}$, $V_{CC_SYNC} = 5\text{ V}$	4.85			V	
V_{OH-15}	High-level SYNC logic output voltage	TPD7S019-15 $I_{OH} = 24\text{ mA}$, $V_{CC_SYNC} = 5\text{ V}$	2			V	
V_{OL}	Low-level SYNC logic output voltage	$I_{OH} = 0\text{ mA}$, $V_{CC_SYNC} = 5\text{ V}$			0.15	V	
V_{OL-15}	Low-level SYNC logic output voltage	TPD7S019-15 $I_{OH} = 24\text{ mA}$, $V_{CC_SYNC} = 5\text{ V}$			0.8	V	
R_T	SYNC driver output resistance	TPD7S019-15	$V_{CC_SYNC} = 5\text{ V}$, SYNC inputs at GND or 3 V			15	Ω
		TPD7S019-55				55	
		TPD7S019-65				65	
C_{IO_VIDEO}	IO capacitance of VIDEO pins	$V_{IO} = 2.5\text{ V}$		2.5	4	pF	
t_{PLH}	SYNC driver L => H propagation delay	$C_L = 50\text{ pF}$; $V_{CC} = 5\text{ V}$, input t_R and $t_F \leq 5\text{ ns}$			12	ns	
t_{PHL}	SYNC driver H => L propagation delay	$C_L = 50\text{ pF}$; $V_{CC} = 5\text{ V}$, input t_R and $t_F \leq 5\text{ ns}$			12	ns	
t_R, t_F	SYNC driver output rise & fall times	$C_L = 50\text{ pF}$; $V_{CC} = 5\text{ V}$, input t_R and $t_F \leq 5\text{ ns}$		4		ns	
V_{BR}	VIDEO ESD diode break-down voltage	$I_{IO} = 1\text{ mA}$	9			V	

Typical Characteristics

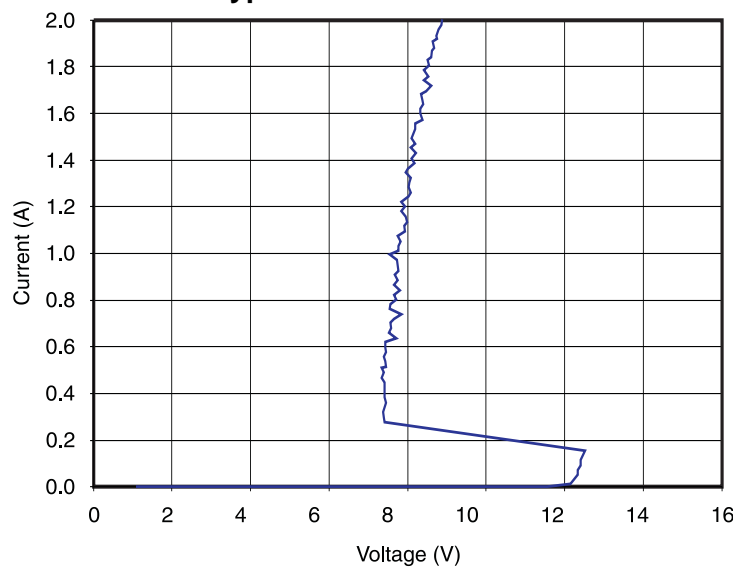


Figure 1. TPD7S019-xx TLP VID1 to GND, Barth, $T_{rf} = 10\text{ ns}$

Typical Characteristics (continued)

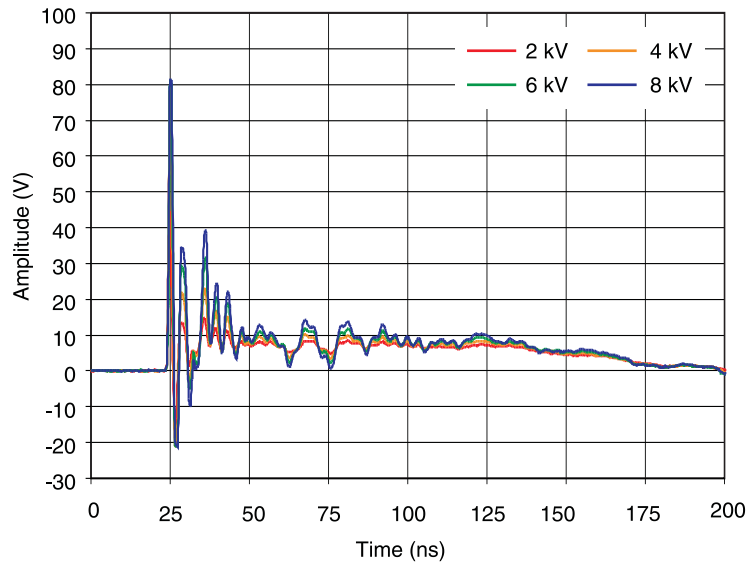


Figure 2. TPD7S019-xx IEC Clamping Waveforms Positive Contact

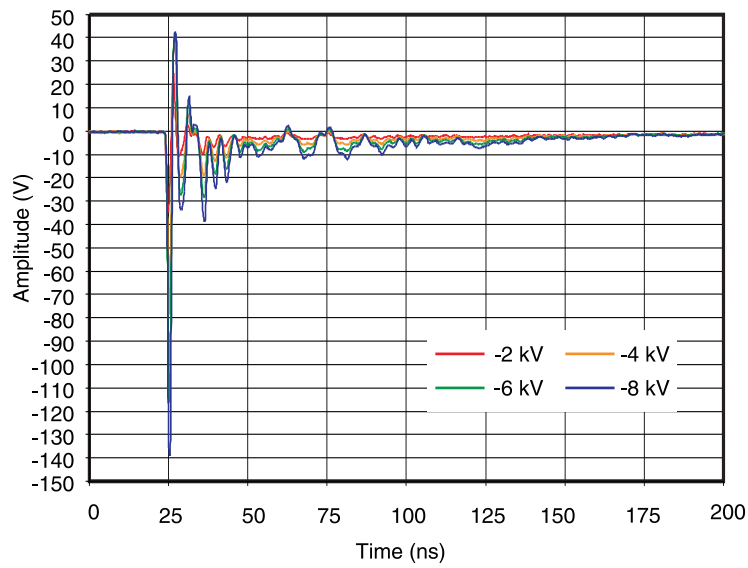


Figure 3. TPD7S019-xx IEC Clamping Waveforms Negative Contact

Typical Characteristics (continued)

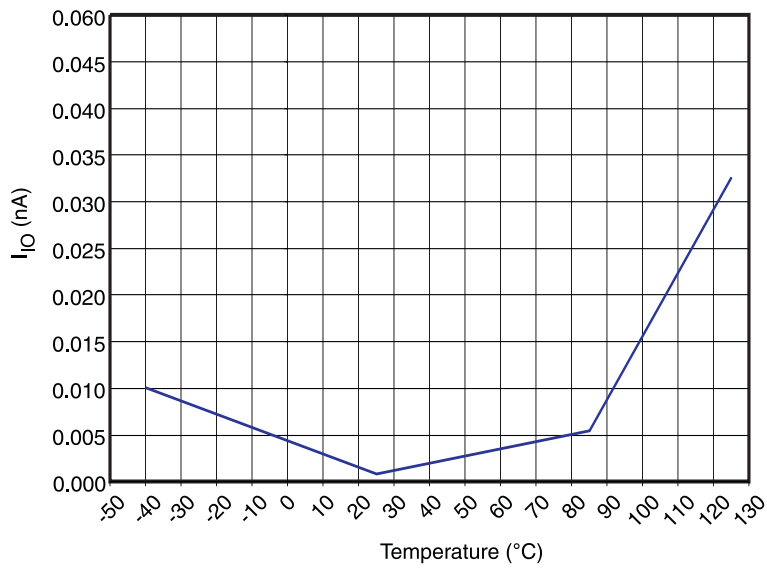


Figure 4. Leakage Current Trough VIDEO Pins
V_{CC_VIDEO} = 5 V

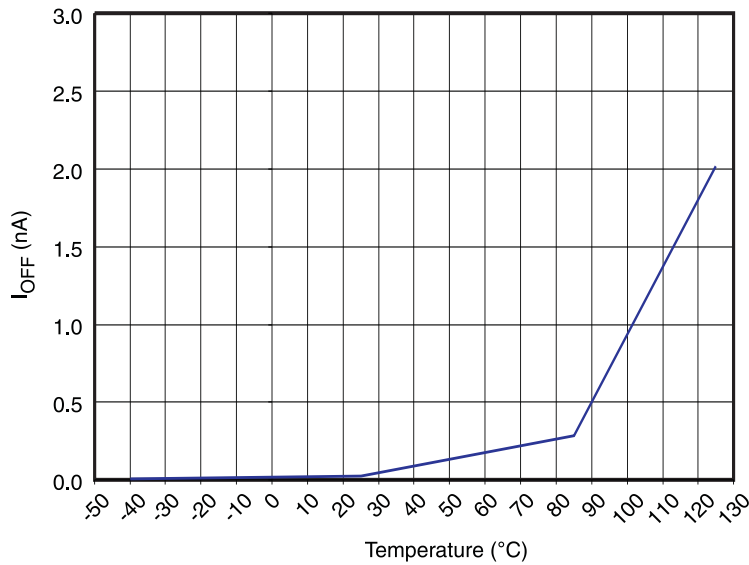


Figure 5. I_{OFF} (DDC_OUTx)
V_{CC_DDC} = 0 V

APPLICATION INFORMATION

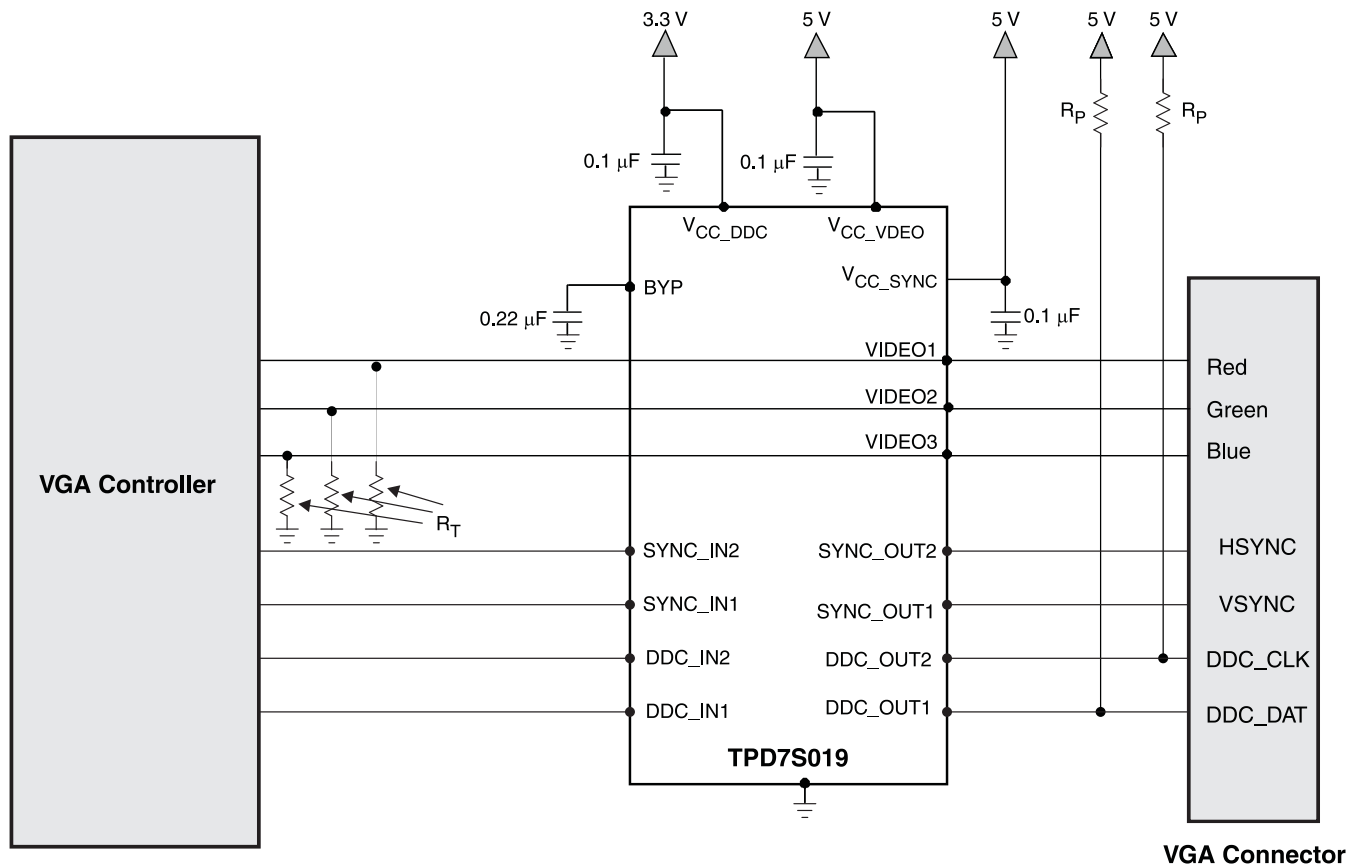


Figure 6. Typical Application Schematics with TPD7S019

R_p : Pullup resistor for the DDC data and clock lines. Typically system designer selects 47 k Ω pullup values

R_T : Line termination resistor for the RGB lines. R_T is selected to match the transmission line. For a single-ended transmission line, R_T can be anywhere from 50 Ω to 75 Ω depending on board trace impedance.

Some systems may require additional filters at the SYNC and RGB lines.

The TPD7S019 should be placed as close to the VGA port as possible.

The ESD protection channels VIDEO1, VIDEO2, VIDEO3 are identical circuits, they can be used interchangeably between the R, G, B signals.

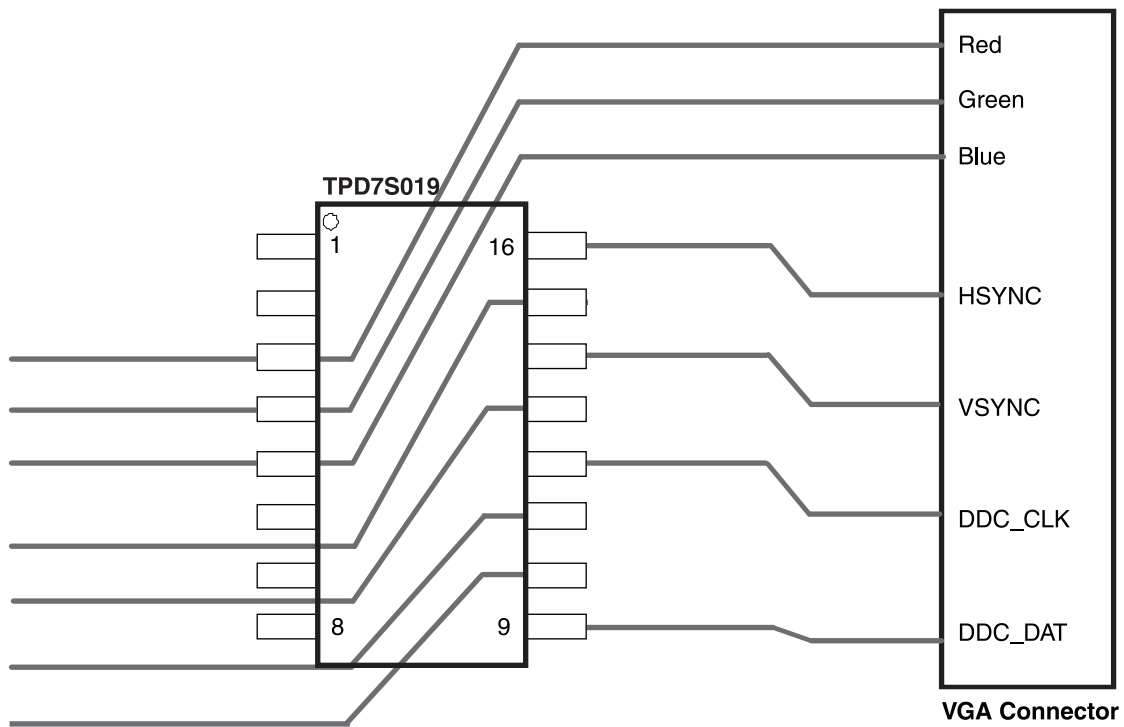


Figure 7. Simplified Layout with TPD7S019 (Only IO Lines are Shown)

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
TPD7S019-15DBQR	ACTIVE	SSOP/QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Request Free Samples
TPD7S019-55DBQR	PREVIEW	SSOP/QSOP	DBQ	16	2500	TBD	Call TI	Call TI	Samples Not Available
TPD7S019-65DBQR	PREVIEW	SSOP/QSOP	DBQ	16	2500	TBD	Call TI	Call TI	Samples Not Available

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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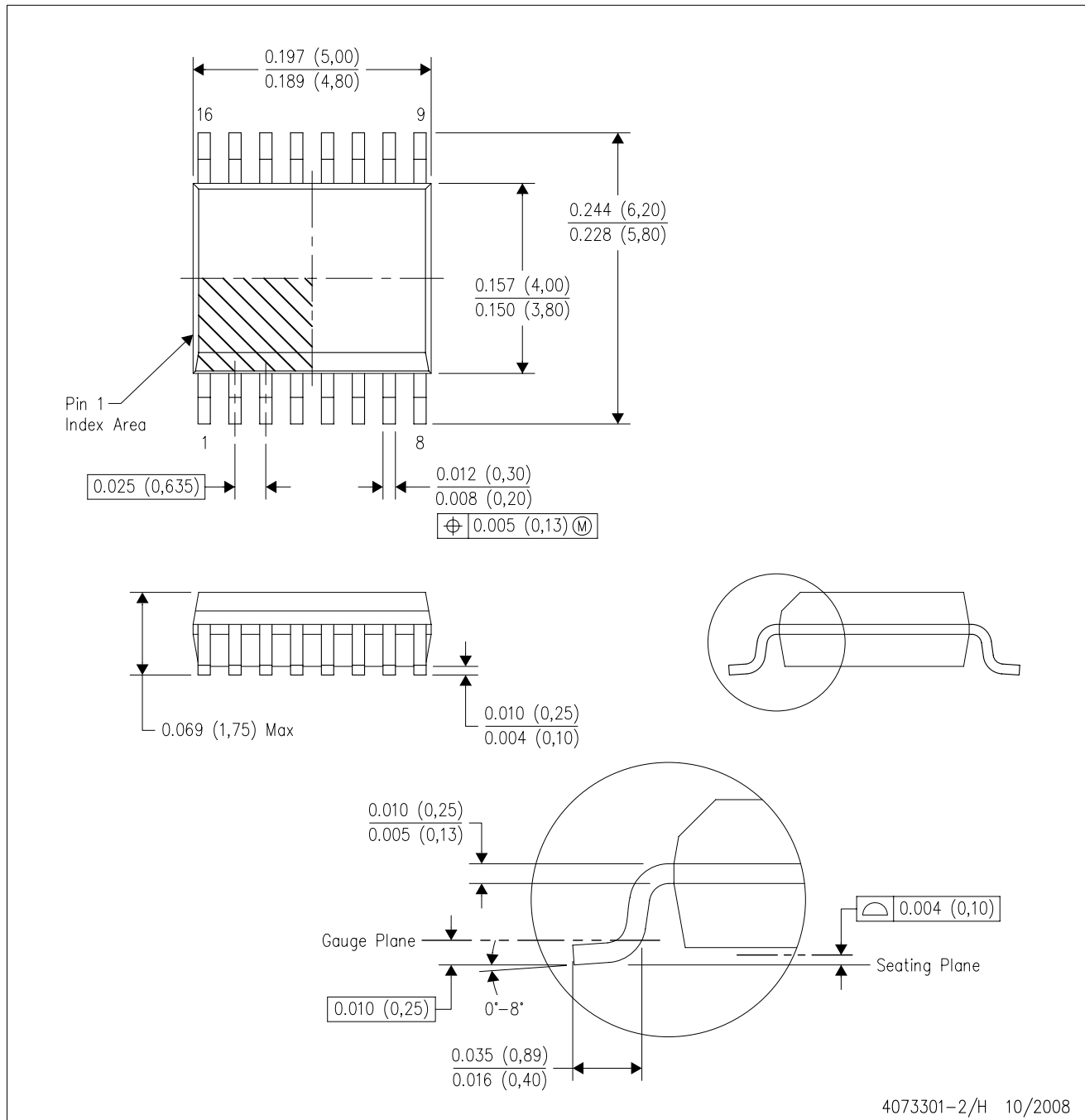
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DBQ (R-PDSO-G16)

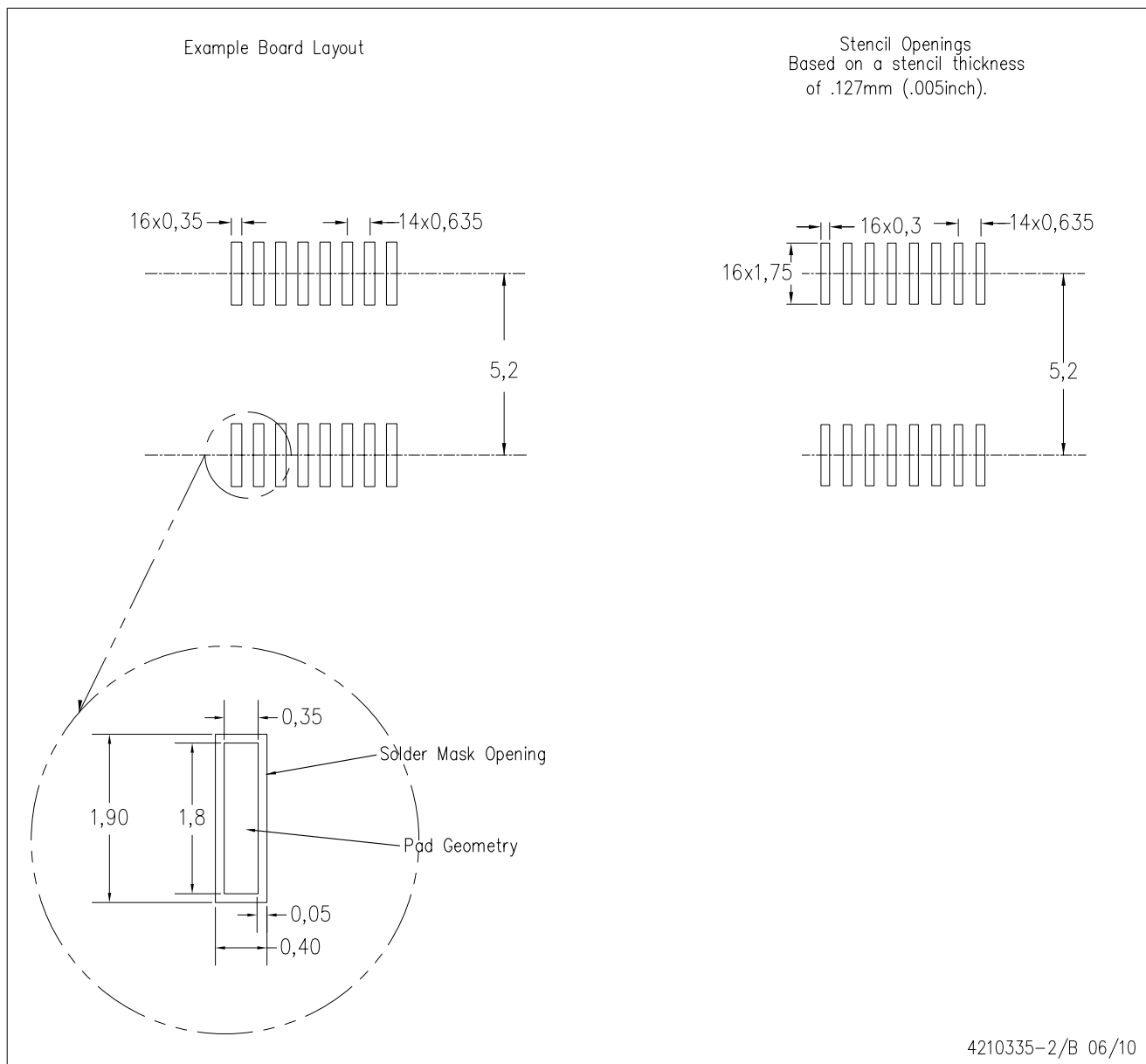
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
 - D. Falls within JEDEC MO-137 variation AB.

DBQ (R-PDSO-G16)

PLASTIC SMALL OUTLINE PACKAGE



4210335-2/B 06/10

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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